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DOCKET NO.: 239360US55DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
HARTWIG KUNZEL ET AL :
SERIAL NO: NEW APPLICATION :
FILED: HEREWITH :
FOR: VAPOR BARRIER FOR USE IN THE :
HEAT INSULATION OF
BUILDINGS

PRELIMINARY AMENDMENT

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Please amend the above-identified application as follows.

Amendments to the specification are set forth on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims that begin on page 3
of this paper.

Remarks begin on page 8 of this paper.

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Amendments to the specification

Page 1, lines 4-7, replace the text in its entirety with the following:

This application is a Divisional of U.S. Patent Application Serial No. 09/521,125 filed March 7, 2000, pending, which is a Continuation-in-part of U.S. Patent Application Serial No. 08/945,146 filed October 17, 1997, abandoned, which is the U.S. national phase of PCT/E96/00705 filed April 18, 1996, which claims priority to German patent application serial number 195 14 420.1 filed April 19, 1995

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This listing of claims will replace the version of claims appended to the accompanying specification.

Listing of the claims

Claims 1-33 (Cancelled).

Claim 34 (New) A method of insulating a building, comprising installing a film component onto the building, wherein the film component has a water vapor diffusion resistance (s_d -value) at a relative humidity of an atmosphere surrounding the vapor retarder in the region of 30% to 50% of 2 to 5 meters diffusion-equivalent air layer thickness, and, at a relative humidity in the region of 60% to 80% which is < 1 meter diffusion-equivalent air layer thickness.

Claim 35 (New) The method of claim 34, wherein the film component is attached to a carrier material.

Claim 36 (New) The method of claim 35, wherein the carrier material has a water vapor diffusion resistance which is less than the water vapor diffusion resistance of the film.

Claim 37 (New) The method of claim 35, wherein the carrier material is selected from the group consisting of particle board, chip board, oriented strand board, plywood paneling, gypsum board, fiber reinforced gypsum board, fiber board, cement board, cementitious wood wool board, calcium silica board, fiber insulation batts, fiber insulation slabs, foam insulation slabs, wall paper, and cloth.

Claim 38 (New) The method of claim 35, wherein the carrier material is a fiber-reinforced cellulose material.

Claim 39 (New) The method of claim 34, wherein the film component is sandwiched between two layers of carrier material, the two layers of carrier material having a water vapor diffusion resistance which is less than the water vapor diffusion resistance of the film.

Claim 40 (New) The method of claim 34, wherein the film component comprises polyamide.

Claim 41 (New) The method of claim 40, wherein the polyamide is selected from the group consisting of polyamide 6, polyamide 4, and polyamide 3.

Claim 42 (New) The method of claim 41, wherein the polyamide is polyamide 6.

Claim 43 (New) The method of claim 34, wherein the film component has a thickness of 10 μm to 2 mm.

Claim 44 (New) The method of claim 34, wherein the film component has a thickness of 20 μm to 100 μm .

Claim 45 (New) The method of claim 34, wherein the film is attached to an inner wall surface of the building.

Claim 46 (New) The method of claim 34, wherein the installing the film comprises spraying or painting the film component onto the building.

Claim 47 (New) The method of claim 34, wherein the film component is a formed film.

Claim 48 (New) The method of claim 47, wherein the film component comprises polyamide.

Claim 49 (New) The method of claim 48, wherein the polyamide is selected from the group consisting of polyamide 6, polyamide 4, and polyamide 3.

Claim 50 (New) The method of claim 49, wherein the polyamide is polyamide 3.

Claim 51 (New) The method of claim 47, wherein the thickness of the formed film is 10 μm to 2 mm.

Claim 52 (New) The method of claim 47, wherein the thickness of the formed film is 20 μm to 100 μm .

Claim 53 (New) The method of claim 47, wherein the formed film is attached to a carrier material.

Claim 54 (New) The method of claim 53, wherein the carrier material is selected from the group consisting of particle board, chip board, oriented strand board, plywood paneling,

gypsum board, fiber reinforced gypsum board, fiber board, cement board, cementitious wood wool board, calcium silica board, fiber insulation batts, fiber insulation slabs, foam insulation slabs, wall paper, and cloth.

Claim 55 (New) The method of claim 53, wherein the carrier material is a fiber-reinforced cellulose material.

Claim 56 (New) The method of claim 47, wherein the formed film is sandwiched between two layers of carrier material, the two layers of carrier material having a water vapor diffusion resistance which is less than the water vapor diffusion resistance of the film.

Claim 57 (New) The method of claim 47, wherein the formed film comprises a pattern.

Claim 58 (New) The method of claim 47, wherein the formed film comprises a printed color pattern.

Claim 59 (New) The method of claim 34, wherein the film component is installed onto a wall of the building.

Claim 60 (New) The method of claim 34, wherein the film component is installed onto a roof of the building.

Claim 61 (New) The method of claim 34, wherein the film component is installed onto a wall and a roof of the building.

Claim 62 (New) The method of claim 47, wherein the formed film is installed onto a wall of the building.

Claim 63 (New) The method of claim 47, wherein the formed film is installed onto a roof of the building.

Claim 64 (New) The method of claim 47, wherein the formed film is installed onto a wall and a roof of the building.